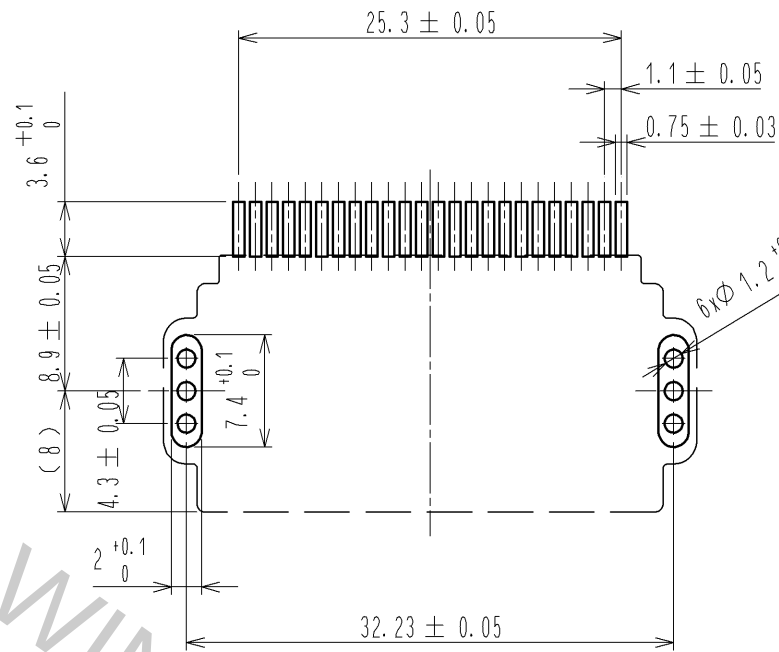
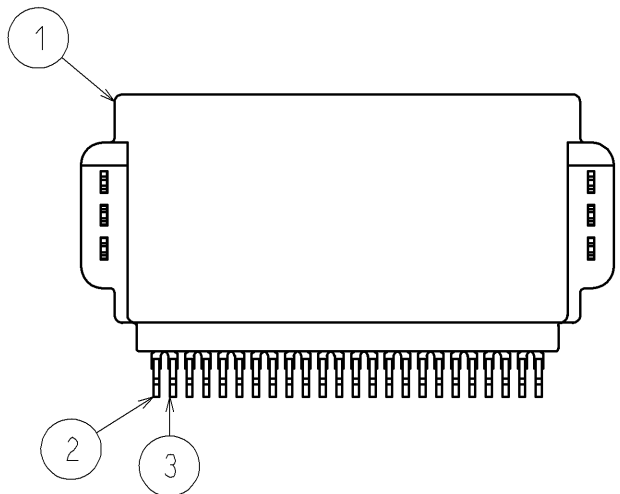
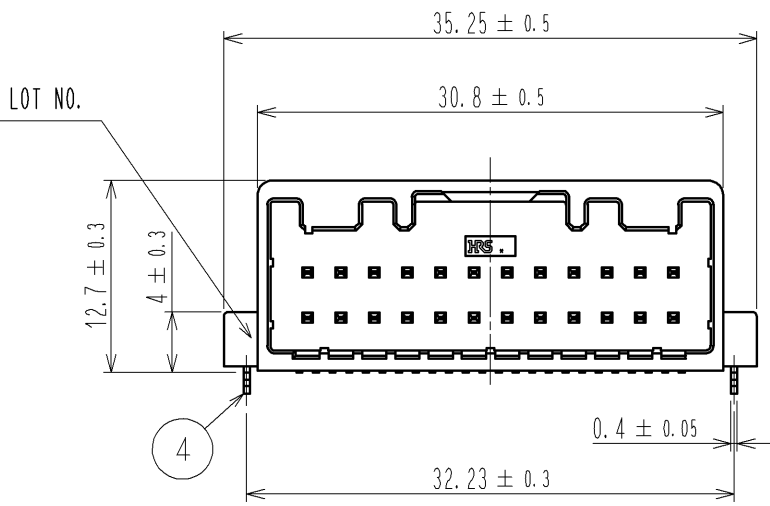
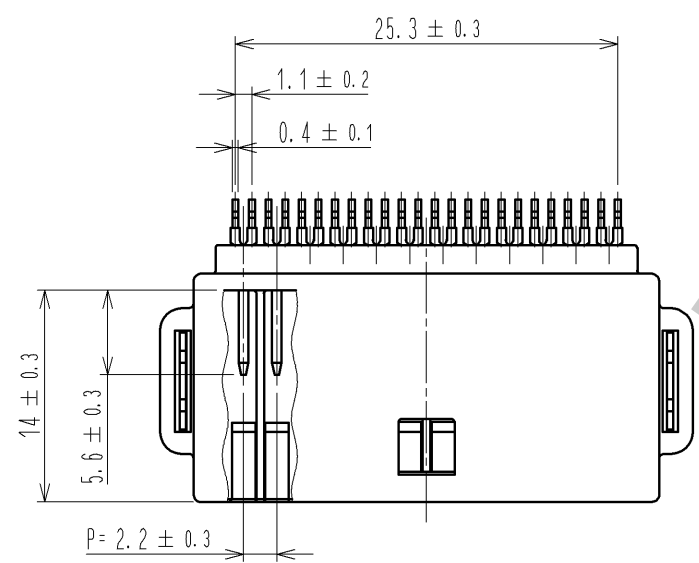
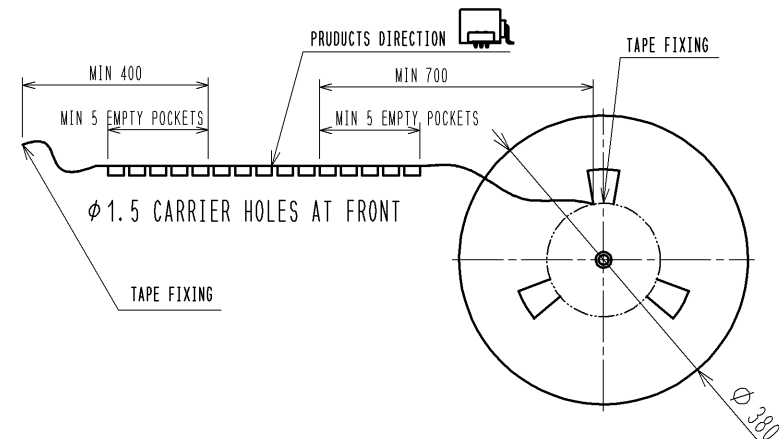


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ELV, RoHS COMPLIANT

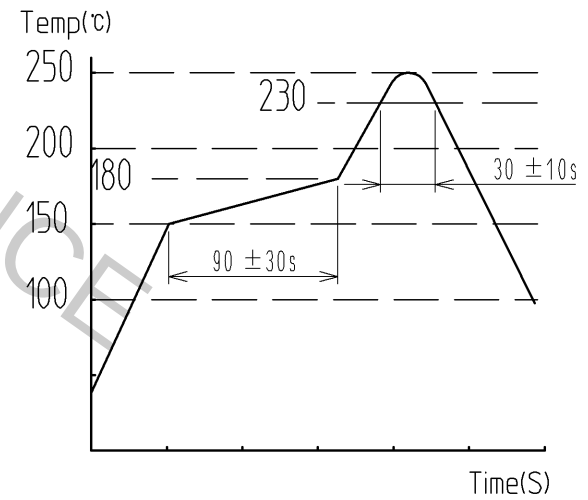


RECOMMENDED PC BOARD PATTERN



EMBOSS SPECULATION

- NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW
(REFER TO RIGHT FIG.)
USED REFLOW SYSTEM
: IR IN THE AIR OR NITROGEN
NO. OF CYCLES : 2 MAX
PEAK : 250℃
OVER 230℃ : 20~40s
PREHEAT : 150~180℃
60~120s
2. TEMPERATURE FOR SOLDERING IRON
: 280~300℃ WITHIN 2s
3. CO-PLANARITY SHALL BE 0.1 MAX.
4. PC BOARD THICKNESS=1.6.
5. RECOMMENDED SOLDER THICKNESS=0.15



2	BRASS	TIN PLATED	T=0.64	4	BRASS	TIN PLATED	T=0.4
1	PPS	LIGHT GRAY		3	BRASS	TIN PLATED	T=0.64
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
UNITS mm		SCALE 2 : 1	COUNT 1	DESCRIPTION OF REVISIONS		DESIGNED TY. SAKASHITA	CHECKED TY. TAKAHASHI
HIROSE ELECTRIC CO., LTD.		APPROVED : KS. SATOH	07.04.25	DRAWING NO. EDC3-166409-00			
		CHECED : AR. SHIRAI	07.04.19	PART NO. GT25-24DP-2.2H			
		DESIGNED : TY. SAKASHITA	07.04.19	CODE NO. CL775-0007-0-00			
		DRAWN : TY. SAKASHITA	07.04.19				